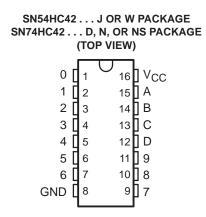
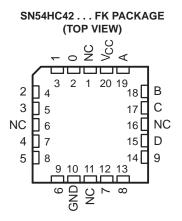
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- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 14 ns
- ±4-mA Output Drive at 5 V



- Low Input Current of 1 μA Max
- Full Decoding of Input Logic
- All Outputs Are High for Invalid BCD Conditions
- Also for Applications as 3-Line to 8-Line Decoders



NC - No internal connection

description/ordering information

These decimal decoders consist of eight inverters and ten 4-input NAND gates. The inverters are connected in pairs to make BCD input data available for decoding by the NAND gates. Full decoding of valid input logic ensures that all inputs remain off for all invalid input conditions.

TA	PACKA	3E†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HC42N	SN74HC42N
–40°C to 85°C		Tube of 40	SN74HC42D	
	SOIC – D	Reel of 2500	SN74HC42DR	HC42
		Reel of 250	SN74HC42DT	
	SOP – NS	Reel of 2000	SN74HC42NSR	HC42
	CDIP – J	Tube of 25	SNJ54HC42J	SNJ54HC42J
–55°C to 125°C	CFP – W	Tube of 150	SNJ54HC42W	SNJ54HC42W
	LCCC – FK	Tube of 55	SNJ54HC42FK	SNJ54HC42FK

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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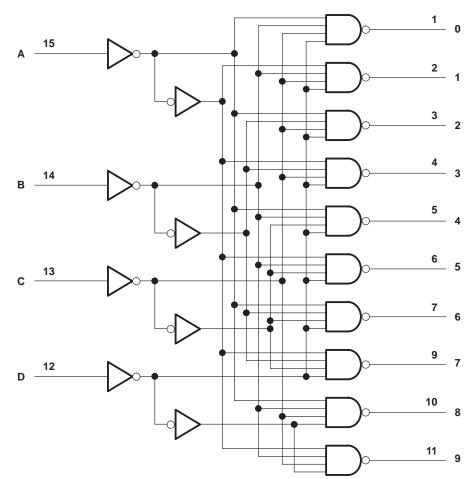
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						FUNC	TION TA	BLE						
NO		INP	UTS						OUT	PUTS				
NO.	D	С	В	Α	0	1	2	3	4	5	6	7	8	9
0	L	L	L	L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н
1	L	L	L	Н	н	L	Н	Н	Н	Н	Н	Н	Н	Н
2	L	L	Н	L	н	Н	L	Н	Н	Н	Н	Н	Н	Н
3	L	L	Н	Н	Н	Н	Н	L	Н	Н	Н	Н	Н	н
4	L	Н	L	L	Н	Н	Н	Н	L	Н	Н	Н	Н	н
5	L	Н	L	Н	Н	Н	Н	Н	Н	L	Н	Н	Н	Н
6	L	Н	Н	L	н	Н	Н	Н	Н	Н	L	Н	Н	Н
7	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L	Н	н
8	Н	L	L	L	Н	Н	Н	Н	Н	Н	Н	Н	L	н
9	Н	L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L
	Н	L	Н	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н
	Н	L	Н	Н	н	Н	Н	Н	Н	Н	Н	Н	Н	Н
Invalid	Н	Н	L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н
mvalid	Н	Н	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н
	Н	Н	Н	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н
	Н	Н	Н	Н	н	Н	Н	Н	Н	Н	Н	Н	Н	Н



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logic diagram (positive logic)



Pin numbers shown are for the D, J, N, NS, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (se Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	ee Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})		±25 mA
Continuous current through V _{CC} or GND		±50 mA
Package thermal impedance, θ_{JA} (see Note 2)	: D package	73°C/W
	N package	67°C/W
	NS package	64°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

			S	N54HC4	2	S	N74HC4	2		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC	Supply voltage		2	5	6	2	5	6	V	
		$V_{CC} = 2 V$	1.5			1.5				
ViH	High-level input voltage	V _{CC} = 4.5 V 3.15				3.15			V	
<u> </u>		$V_{CC} = 6 V$	4.2			4.2				
		$V_{CC} = 2 V$			0.5			0.5		
VIL	Low-level input voltage	$V_{CC} = 4.5 V$			1.35			1.35	V	
		$V_{CC} = 6 V$			1.8			1.8		
VI	Input voltage		0		VCC	0		VCC	V	
VO	Output voltage		0		VCC	0		VCC	V	
		$V_{CC} = 2 V$			1000			1000		
Δt/Δv	Input transition rise/fall time	V _{CC} = 4.5 V			500			500	ns	
		$V_{CC} = 6 V$			400			400		
TA	Operating free-air temperature		-55		125	-40		85	°C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST CONDITIONS			Т	A = 25°C	;	SN54	HC42	SN74H	IC42	
PARAMETER	TEST CO	INDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4		
VOH	V _{OH} V _I = V _{IH} or V _{IL}		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		I _{OH} = -5.2 mA	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
VOL	$V_{I} = V_{IH} \text{ or } V_{IL}$		6 V		0.001	0.1		0.1		0.1	V
		I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		I _{OL} = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC} \text{ or } 0$		6 V		±0.1	±100		±1000		±1000	nA
ICC	$V_I = V_{CC} \text{ or } 0,$	IO = 0	6 V			8		160		80	μA
Ci			2 V to 6 V		3	10		10		10	pF



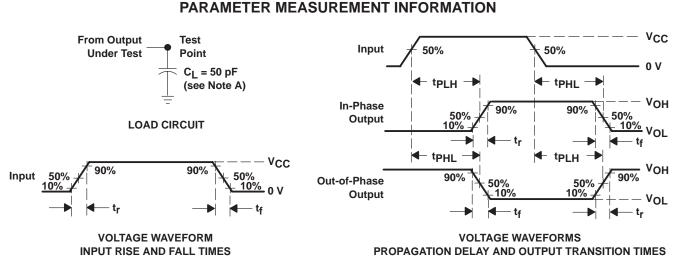
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switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

	FROM	то		T _A = 25°C			SN54HC42		SN74HC42			
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
		, or D 0–9 4	2 V		65	150		225		190		
^t pd	A, B, C, or D		4.5 V		18	30		45		38	ns	
			6 V		14	26		38		32		
			2 V		28	75		110		95		
tt		Any	4.5 V		8	15		22		19	ns	
			6 V		7	13		19		16		

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
Cpd	Power dissipation capacitance	No load	39	pF



NOTES: A. CL includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns, t_f = 6 ns.
- C. The outputs are measured one at a time with one input transition per measurement.
- D. tpLH and tpHL are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms





24-Aug-2018

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-86821012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 86821012A SNJ54HC 42FK	Samples
5962-8682101EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8682101EA SNJ54HC42J	Samples
SN54HC42J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54HC42J	Samples
SN74HC42D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC42	Samples
SN74HC42DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC42	Samples
SN74HC42DT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC42	Samples
SN74HC42N	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC42N	Samples
SNJ54HC42FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 86821012A SNJ54HC 42FK	Samples
SNJ54HC42J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8682101EA SNJ54HC42J	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.



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⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54HC42, SN74HC42 :

Catalog: SN74HC42

• Military: SN54HC42

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

P1

(mm)

8.0

K0

(mm)

2.1

w

(mm)

16.0

Pin1

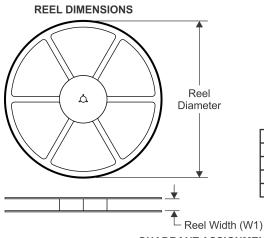
Quadrant

Q1

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TAPE AND REEL INFORMATION



SN74HC42DR



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



330.0

16.4

6.5

10.3

*All dimensions are nominal							
Device	•	Package Drawing		Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)

16

2500

D

SOIC

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

18-Aug-2014



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC42DR	SOIC	D	16	2500	333.2	345.9	28.6

LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



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D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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